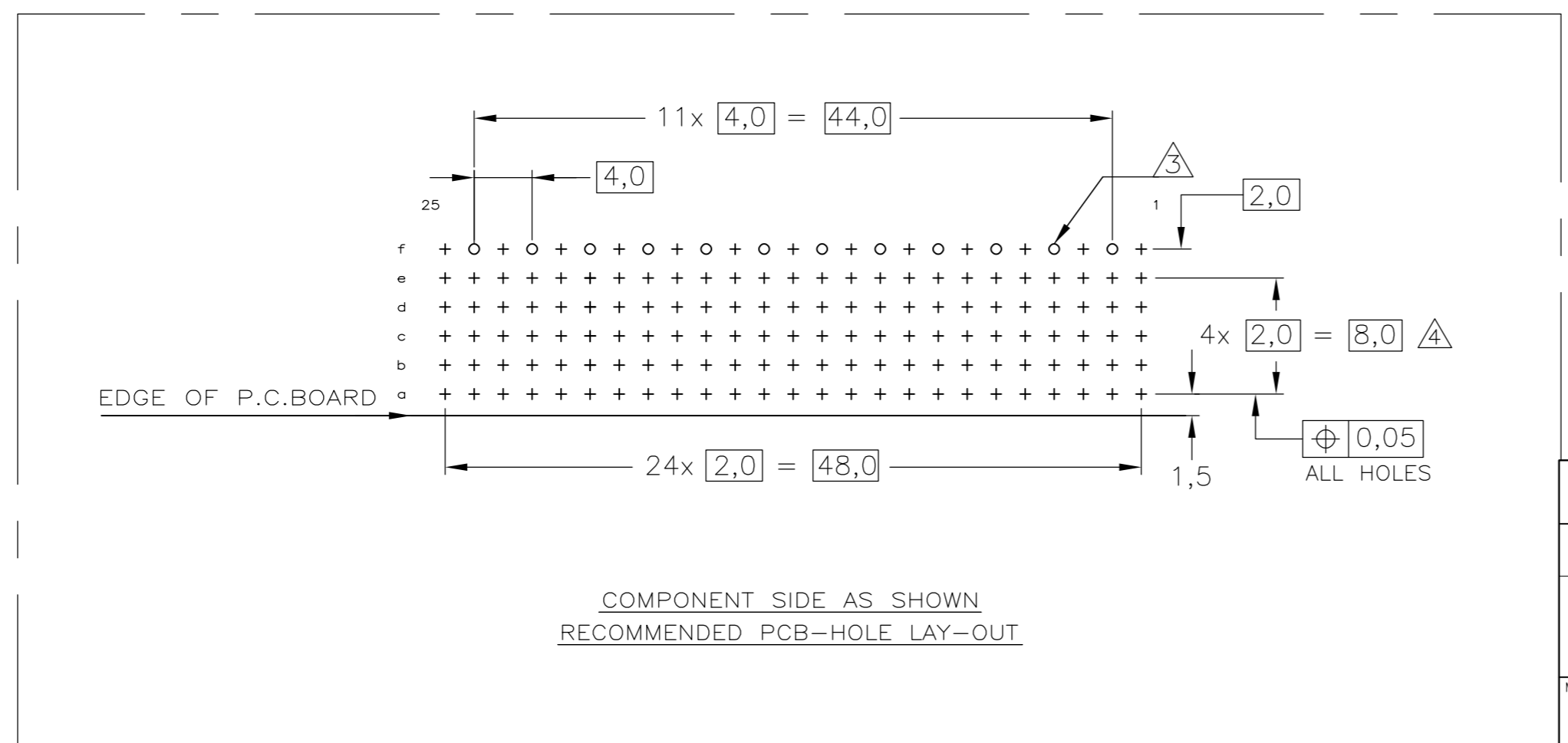
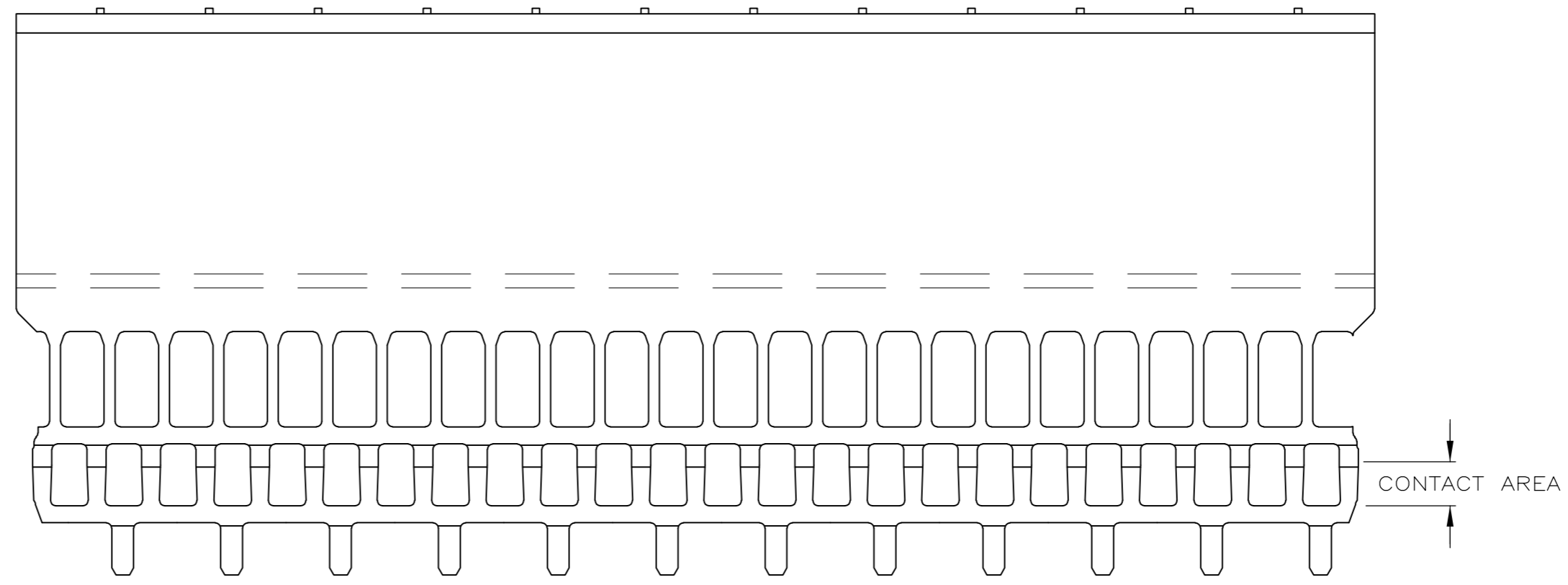
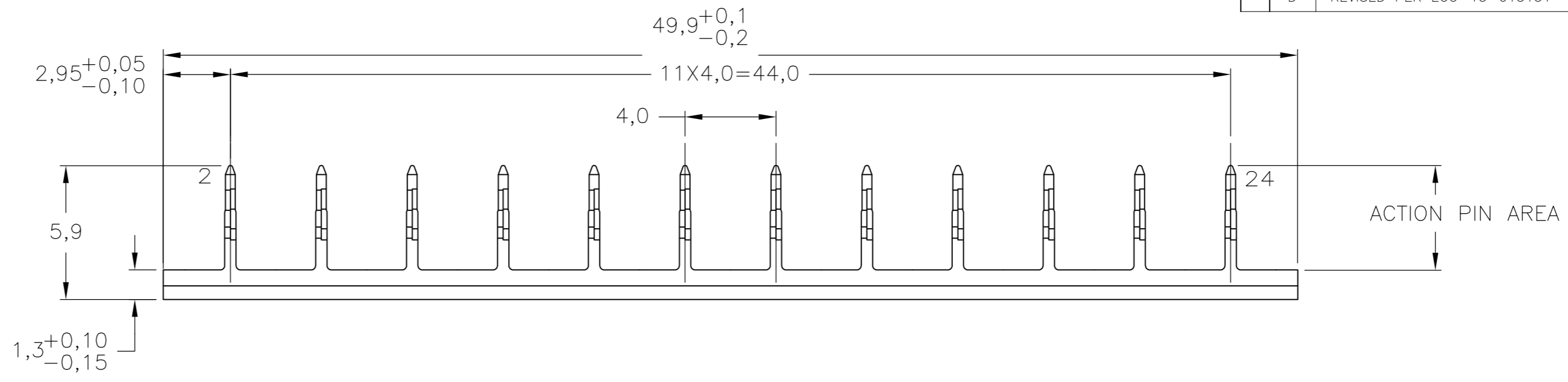
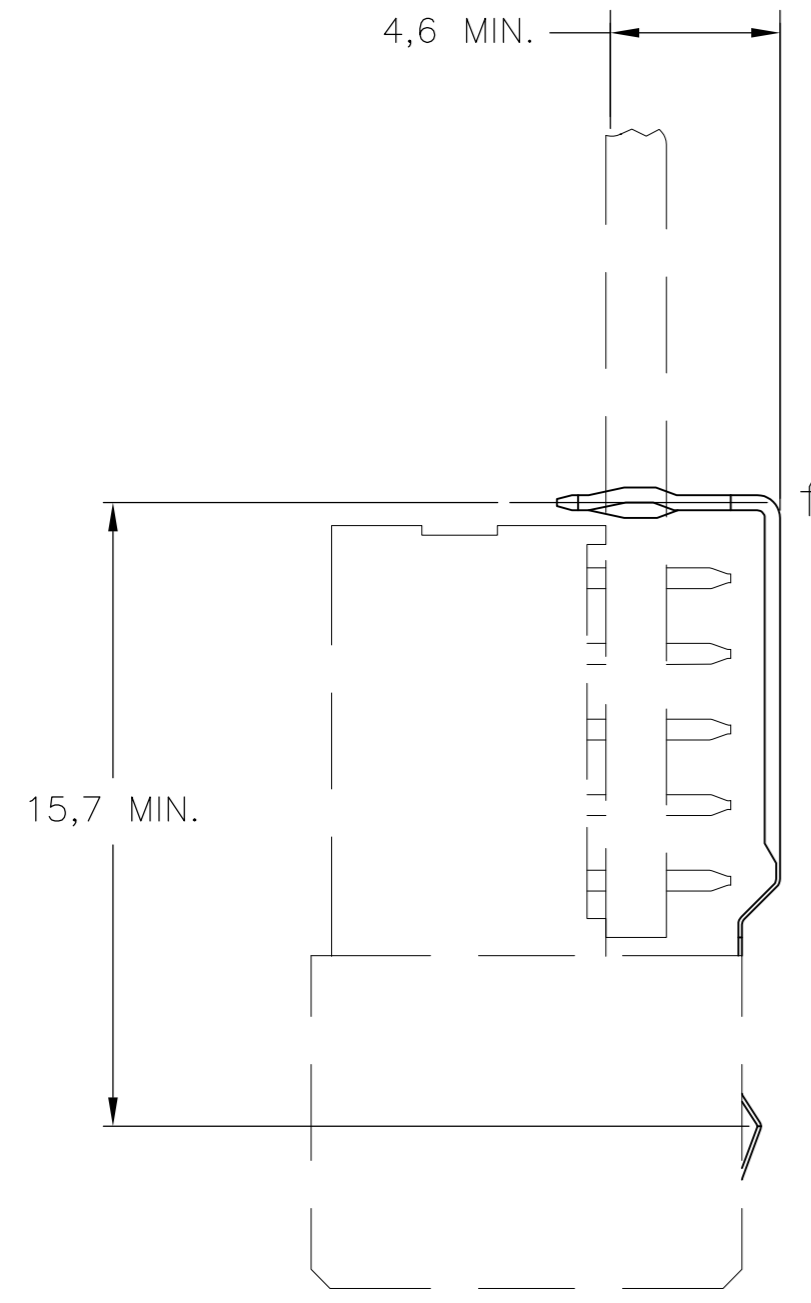


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LOC		DIST		REVISIONS			
P	LTR	DESCRIPTION		DATE	DWN	APVD	
H	-	D	REVISED PER ECO-13-015151	16DEC2013	FL	FY	



NOTES:

- ① GENERAL PLATING SPECIFICATION: UNDERPLATING (ENTIRE CONTACT): 1,27μm NICKEL MIN. AND ACTION PIN: 0,5μm TIN MIN. FOR PLATING OF MATING SURFACES SEE PERFORMANCE LEVEL SHOWN IN PART NUMBER TABLE.
- ② MATERIAL; PHOSPHORBRONZE.
- ③ ROW "f" 12 PLATED THROUGH HOLES FOR LOWERSHIELD.
- ④ HOLE PATTERN FOR FEMALE CONNECTOR TYPE B-25 COLUMNS WITH UPPERSHIELD, 125+13 PLATED-THROUGH HOLES AT 2x2mm SQUARE GRID.
- ⑤ MAX. BOARD THICKNESS 3,5 mm.
- ⑥ SHIELDS LUBRICATED WITH BELLCORE APPROVED LUBRICANT. TECHNICAL REF: TR-NWT-001217 ISSUE 1, SEPT. 1992.
- ⑦ CONFORMS TO ALL TESTING ACCORDING IEC 61076-4-101 PERFORMANCE LEVEL 2.
- ⑧ CONFORMS TO ALL TESTING ACCORDING IEC 61076-4-101 PERFORMANCE LEVEL 1.
- ⑨ CONNECTOR TESTED AND QUALIFIED AGAINST TELCORDIA GR-1217-CORE QUALITY LEVEL III, CENTRAL OFFICE APPLICATIONS.
- ⑩ 0.76μm MIN GOLD PLATING AT MATING SURFACE.

FINISH	MATERIAL	PARTNUMBER
① ③ ⑩	②	4-5338110-0
① ⑥ ⑨	②	5338110-9
① ③	②	5338110-2

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN K.N.KIRAN 13AUG04	TE Connectivity	
DIMENSIONS: mm	TOLERANCES UNLESS OTHERWISE SPECIFIED: ±0.2	CHK B.MOOIJ 25MAR05	Z-PACK 2mm HM GROUND RETURN LOWER SHIELD TYPE B-25 COLUMNS	
	① PLG ±	APVD B.MOOIJ 25MAR05	NAME	RESTRICTED TO
	② PLG ±	PRODUCT SPEC	108-19082	
	③ PLG ±	APPLICATION SPEC	114-19029	
	④ PLG ±	WEIGHT	-	
MATERIAL	FINISH	CUSTOMER DRAWING	SCALE 5:1	SHEET 1 OF 1

5338110

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单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)